

Spark Gap (SPG) Data Sheet

Features

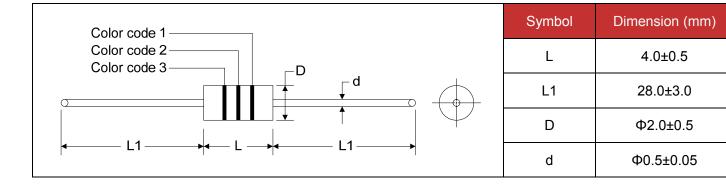
- Approximately zero leaking current before clamping voltage
- Less decay at on/off state.
- High capability to withstand repeated lightning strikes.
- Low electrode capacitance(≤0.8pF) and high isolation(≥100MΩ).
- RoHS compliant.
- Bilateral symmetrical.
- Temperature, humidity and lightness insensitive.
- Operating temperature: -40°C ~ +85°C
- Storage temperature: -40°C ~ +125°C
- Meets MSL level 1, per J-STD-020
- Safety certification: UL: E244458



Applications

- Power Supplies
- Motor sparks eliminating
- Relay switching spark absorbing
- Data line pulse guarding
- Electronic devices requiring UL497A and UL497B compliant
- Telephone/Fax/Modem
- High frequency signal transmitters/receivers
- Satellite antenna
- Radio amplifiers
- Alarm systems
- Cathode ray tubes in Monitors/TVs

Dimensions





Electrical Characteristics

Part Number ①	DC Spark-over Voltage	Minimum Insulation Resistance		Maximum Capacitance (1KHz-6V _{MAX})	Surge current capacity	Surge Life Test
	Vs(V)	Test Voltage(V)	IR _{OHM} (MΩ)	C(pf)	(8/20µs)	8/20µs,100A
BK3XX00702	140	50	100	0.8	500A	150 times
BK3XX01002	200	100	100	8.0	500A	150 times
BK3XX01102	220	100	100	0.8	500A	150 times
BK3XX01502	300	100	100	0.8	500A	150 times
BK3XX02002	400	250	100	0.8	500A	150 times
BK3XX02502	500	250	100	0.8	500A	150 times
BK3XX03002	600	250	100	0.8	500A	150 times
BK3XX03502	700	250	100	0.8	500A	150 times
BK3XX05002	1000	500	100	0.8	500A	150 times
BK3XX07502	1500	500	100	0.8	500A	150 times

Note: 1 Vs±XX%

Color Code

Part Number	Color Code 1	Color Code 2	Color Code 3
BK3XX00702	Black	Yellow	-
BK3XX01002	Red	-	-
BK3XX01102	Red	Red	-
BK3XX01502	Orange	Orange	-
BK3XX02002	Yellow	-	-
BK3XX02502	Green	-	
BK3XX03002	Blue	-	-
BK3XX03502	White	Brown	-
BK3XX05002	Black	-	-
BK3XX07502	Brown	Green	Red

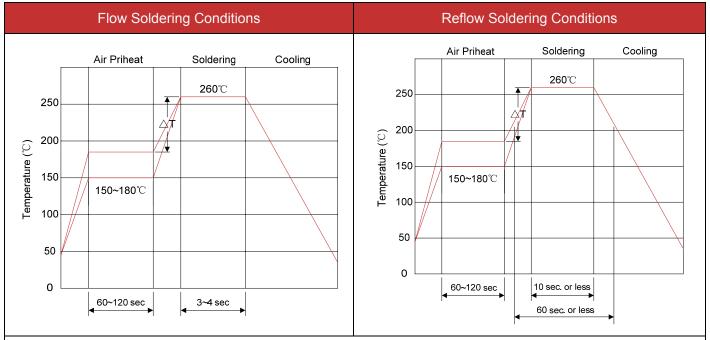


Test Methods and Results

Items	Test Method		Standard	
DC Spark-over Voltage	gradually incre current is 0.5r	ing discharge voltage (Vs) by easing applied DC voltage. Test mA max. And the DC voltage ithin 100V/s(Vs<1000V) or 000V).		
Insulation Resistance	terminal at req	nsulation resistance across the gular voltage. But the test voltage he DC spark-over voltage.	Meet specified value.	
Capacitance		electrostatic capacitance by tage of less than 6V (at 1KHz) inals.		
Static Life		Oopf condenser is discharged sistor. 200 times at an interval of	△Vs/Vs ≤30% Characteristics of other items must meet the specified value.	
	current applie	impulse current for specified d ±5 times, each time interval 60 reafter, outer appearance shall amined.		
Surge Current Capacity	Туре	Impulse current	No crack and no failures	
	Vs < 400V	1.2/50µs & 8/20µs, 500A		
	Vs ≥ 400V	1.2/50μs & 8/20μs, 500A, electrically connected with a resistor (1~2 Ω).		
Cold Resistance	Measurement temperature/2	after -40℃/1000 HRS & normal HRS.	Features are conformed to rated spec.	
Heat Resistance	Measurement temperature/2	after 125℃/1000 HRS & normal HRS.		
Humidity Resistance		after humidity 90~95℃(45℃) normal temperature/2 HRS.		
Temperature Cycle	→normal, tem	tition of cycle -40℃/30min np/2 min →125℃/30min, after normal temp/2 HRS.		
Solder Ability	230±5℃ for 3	I immerse in molten solder sec up to the point of 1.5mm from or solder adhesion.	Lead wire is evenly covered by solder.	
Solder Heat		after lead wire is dipped up to 5mm from body into 260±5 $^{\circ}$ C ec.	Conformed to rated spec.	
Pull Strength	Apply 0.5kg lo	pad for 10sec.	Lead shall not pull out to snap.	
Flexural Strength		e at the point of 2mm from body ad and back to its original point.		



Recommended Soldering Conditions



- 1) Time shown in the above figures is measured from the point when chip surface reaches temperature.
- 2) Temperature difference in high temperature part should be within 110°C.
- 3) After soldering, do not force cool, allow the parts to cool gradually.

Hand Soldering

Solder iron temperature: 350±5°C Heating time: 3 seconds max.

General attention to soldering

- High soldering temperatures and long soldering times can cause leaching of the termination, decrease in adherence strength, and the change of characteristic may occur.
- ullet For soldering, please refer to the soldering curves above. However, please keep exposures to temperatures exceeding 200 $^{\circ}$ C to fewer than 50 seconds.
- Please use a mild flux (containing less than 0.2wt% CI). Also, if the flux is water soluble, be sure to wash thoroughly to remove any residue from the underside of components that could affect resistance.

Cleaning

When using ultrasonic cleaning, the board may resonate if the output power is too high. Since this vibration can cause cracking or a decrease in the adherence of the termination, we recommend that you use the conditions below.

Frequency: 40kHz max.
Output power: 20W/liter

Cleaning time: 5 minutes max.



Packaging

